

FIG. 1 (Prior Art)

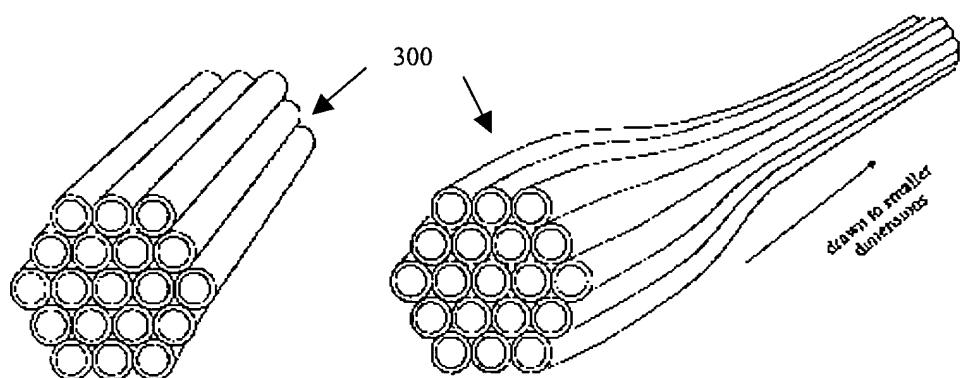


FIG. 2 (Prior Art)

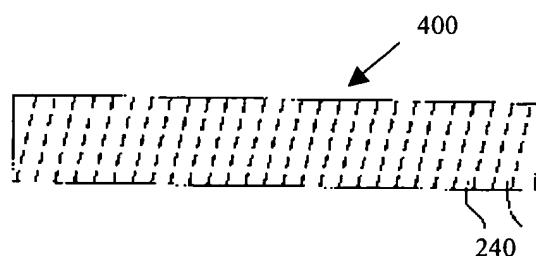


FIG. 3 (Prior Art)

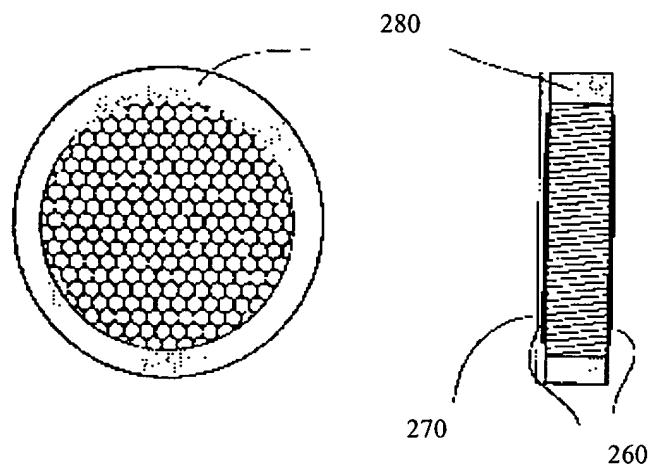


FIG. 4 (Prior Art)

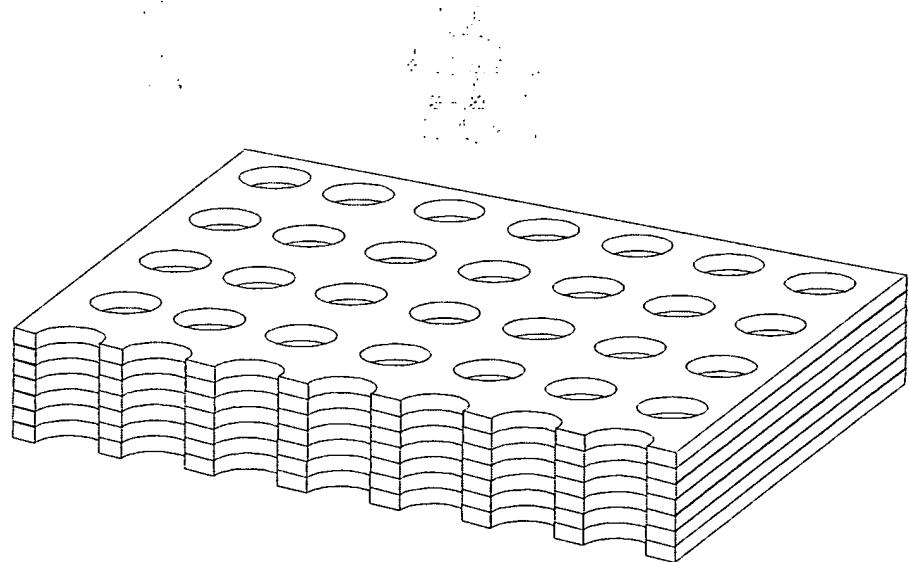


FIG. 5 (Prior Art)

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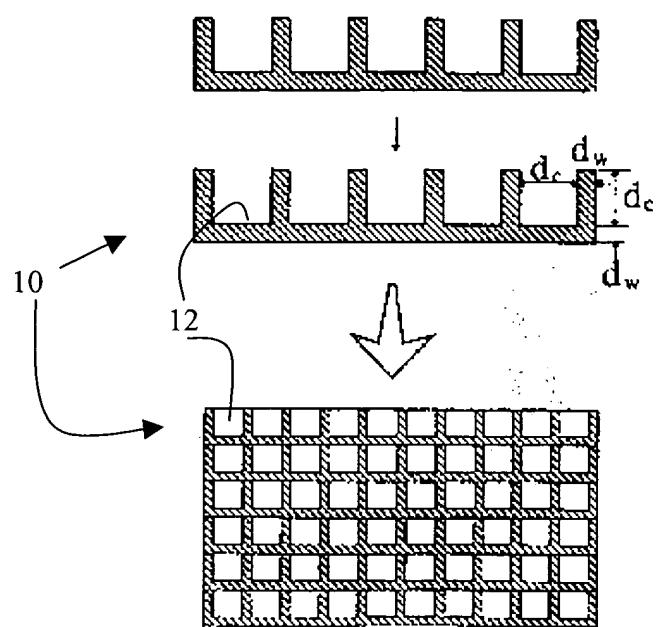
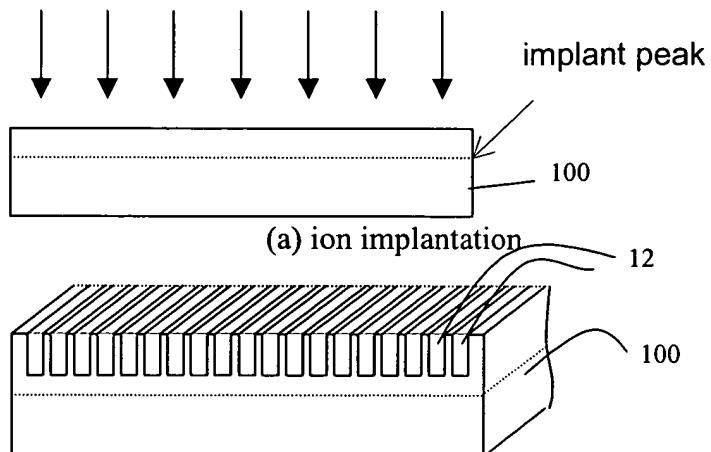
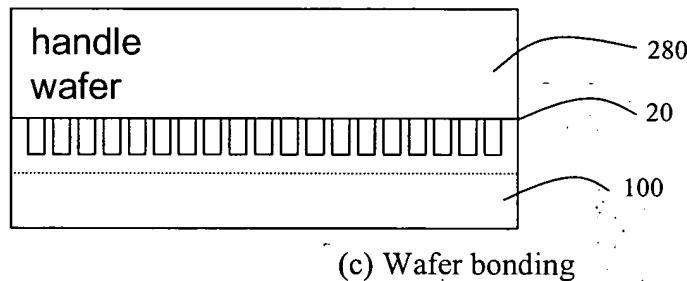


FIG. 6

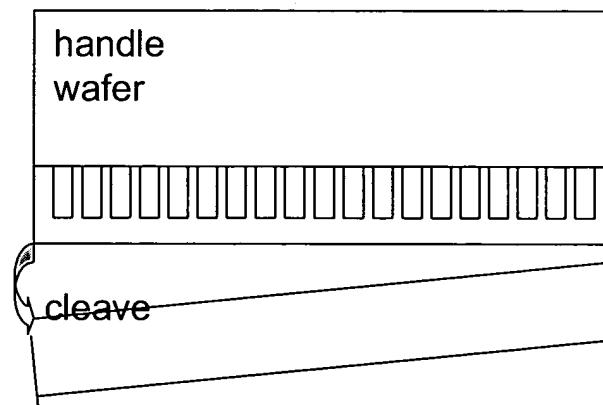
H_2^+ implantation



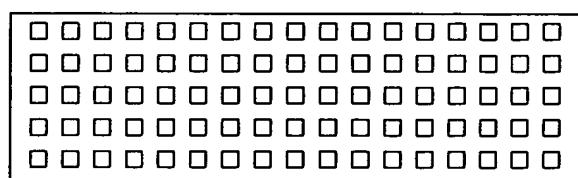
(b) patterning, oxidation and gain enhancement layer coating of the ion implanted wafer



(c) Wafer bonding



(d) Cleaving thin patterned and processed layer



(e) formation of MCP structure by repeating step (a) to (d)

FIG. 7

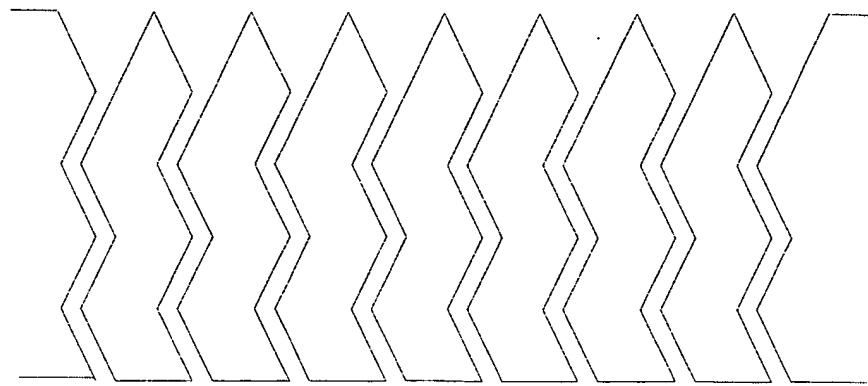


FIG. 8

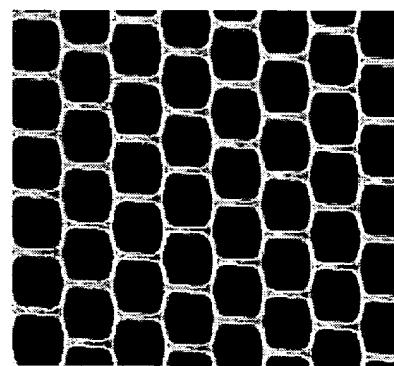


FIG. 9

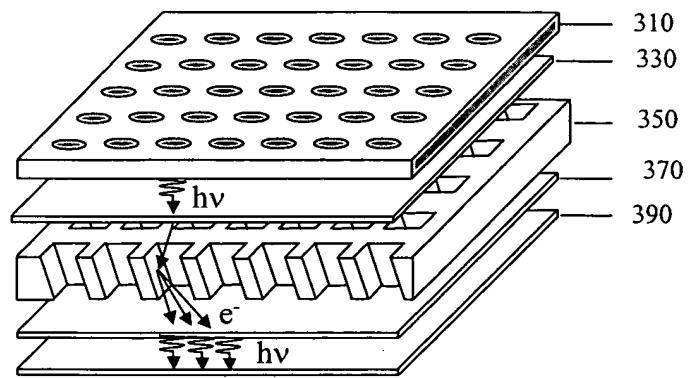


FIG. 10

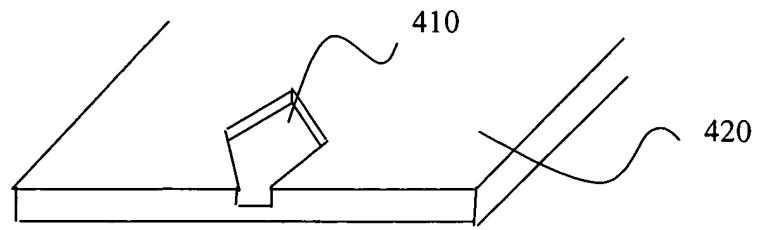


FIG. 11

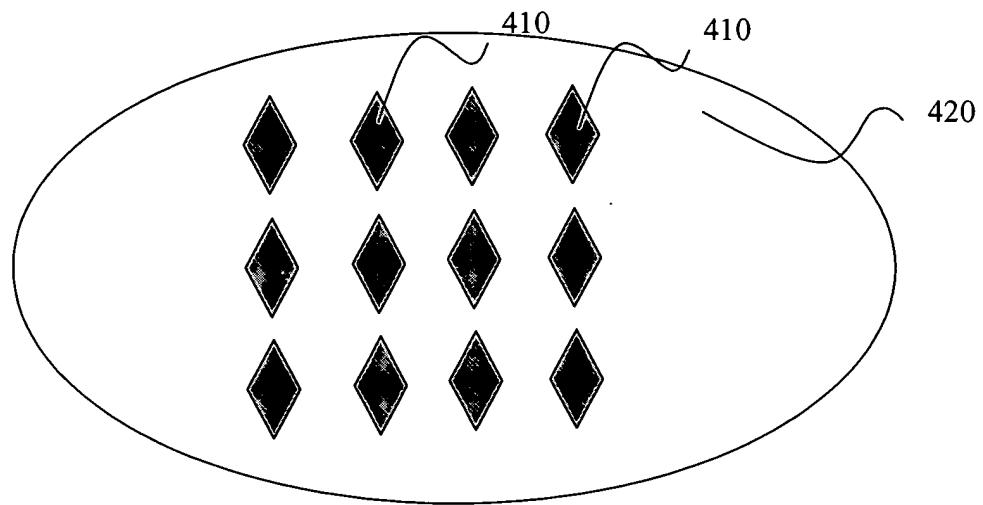


FIG. 12

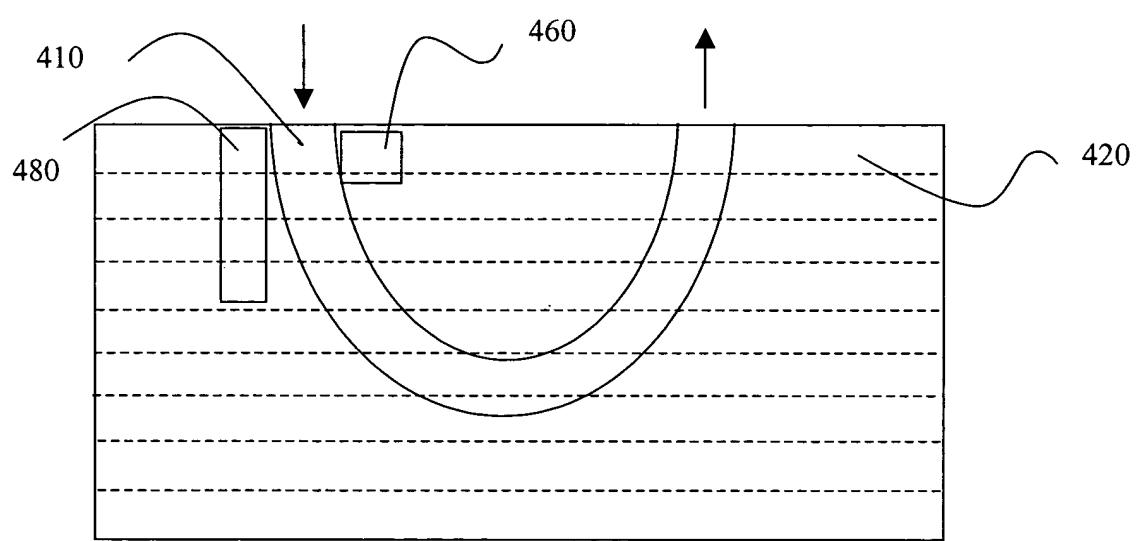


FIG. 13